

N-Channel RF Amplifier MMBF5484, MMBF5485, MMBF5486

This device is designed primarily for electronic switching applications such as low On Resistance analog switching. Sourced from Process 50.

ABSOLUTE MAXIMUM RATINGS* (T_A = 25°C unless otherwise noted)

Symbol	Rating	Value	Unit
V_{DG}	Drain-Gate Voltage	25	V
V _{GS}	Gate-Source Voltage	-25	V
I_{GF}	Forward Gate Current	10	mA
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

*These rating are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1. These rating are based on a maximum junction temperature of 150°C.
- 2. These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

		Max	
Symbol	Characteristic	*MMBF5484-5486	Unit
P _D	Total Device Dissipation Derate above 25°C	225 1.8	mW mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	ı	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	556	°C/W

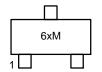
1



NOTE: Source & Drain are interchangeable

SOT-23 CASE 318

MARKING DIAGRAM



6x = Device Code (x = B, M, H)

M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBF5484	SOT-23	3000 Tape &
MMBF5485	(Pb-Free)	Reel
MMBF5486		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}Device mounted on FR-4 PCB 1.6" x 1.6" x 0.06".

$\textbf{ELECTRICAL CHARACTERISTICS} \; (T_J = 25^{\circ}C \; \text{unless otherwise noted})$

Symbol	Parameter	Test Condition		Min	Тур	Max	Unit
OFF CHAI	RACTERISTICS					•	•
$V_{(BR)GSS}$	Gate-Source Breakdown Voltage	$I_G = -1.0 \mu A, V_{DS} = 0$		-25	_	_	V
I _{GSS}	Gate Reverse Current	V _{GS} = -20 V, V _{DS} = 0 V _{GS} = -20 V, V _{DS} = 0, T _A = 100°C		-	- -	-1.0 -0.2	nA μA
V _{GS(off)}	Gate-Source Cutoff Voltage	V _{DS} = 15 V, I _D = 10 nA	5484 5485 5486	-0.3 -0.5 -2.0	- - -	-3.0 -4.0 -6.0	V V V
ON CHAR	ACTERISTICS				-	-	
I _{DSS}	Zero-Gate Voltage Drain Current*	$V_{DS} = 15 \text{ V}, V_{GS} = 0$	5484 5485 5486	1.0 4.0 8.0	- - -	5.0 10 20	mA mA mA
SMALL SI	GNAL CHARACTERISTICS		•		•	1	•
9fs	Forward Transfer Conductance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ kHz}$	5484 5485 5486	3000 3500 4000	- - -	6000 7000 8000	μmhos μmhos μmhos
Re ₍ y _{is)}	Input Conductance	V _{DS} = 15 V, V _{GS} = 0, f = 100 MHz	5484	-	_	100	μmhos
		V _{DS} = 15 V, V _{GS} = 0, f = 400 kHz	5485 / 5486	-	-	1000	μmhos
gos	Output Conductance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ kHz}$	5484 5485 5486	- - -	- - -	50 60 75	μmhos μmhos μmhos
Re ₍ y _{os)}	Output Conductance	V _{DS} = 15 V, V _{GS} = 0, f = 100 MHz	5484	-	_	75	μmhos
		V _{DS} = 15 V, V _{GS} = 0, f = 400 MHz	5485 / 5486	-	-	100	μmhos
Re ₍ y _{fs)}	Forward Transconductance	V _{DS} = 15 V, V _{GS} = 0, f = 100 MHz	5484	2500	_	-	μmhos
		V _{DS} = 15 V, V _{GS} = 0, f = 400 MHz	5485 5486	3000 3500	_ _	- -	μmhos μmhos
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$		-	_	5.0	pF
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$		_	-	1.0	pF
C _{oss}	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$		_	_	2.0	pF
NF	Noise Figure	$V_{DS} = 15 \text{ V}, R_G = 1.0 \text{ k}\Omega, f = 100 \text{ MHz}$	5484	-	_	3.0	dB
		$V_{DS} = 15 \text{ V}, R_G = 1.0 \text{ k}\Omega, f = 400 \text{ MHz}$	5484	-	4.0	_	dB
		$V_{DS} = 15 \text{ V}, R_G = 1.0 \text{ k}\Omega, f = 100 \text{ MHz}$	5485 / 5486	-	_	2.0	dB
		$V_{DS} = 15 \text{ V}, R_G = 1.0 \text{ k}\Omega, f = 400 \text{ MHz}$	5485 / 5486	-		4.0	dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

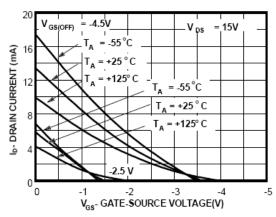


Figure 1. Transfer Characteristics

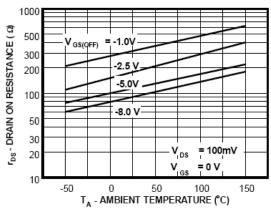


Figure 2. Channel Resistance vs. Temperature

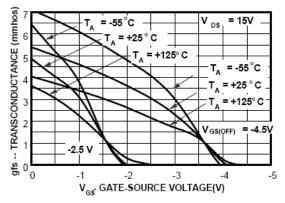


Figure 3. Transconductance Characteristics

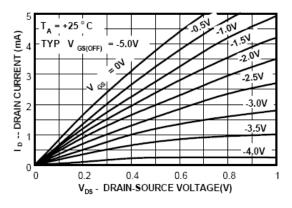


Figure 4. Common Drain-Source Characteristics

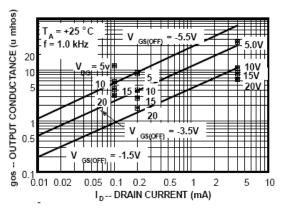


Figure 5. Output Conductance vs. Drain Current

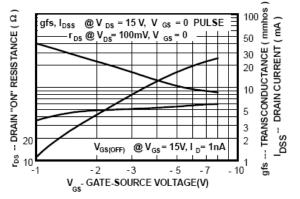


Figure 6. Transconductance Parameter Interactions

TYPICAL CHARACTERISTICS (CONTINUED)

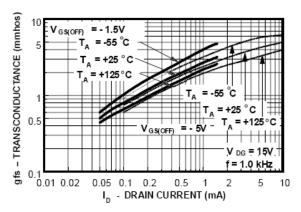


Figure 7. Transconductance vs. Drain Current

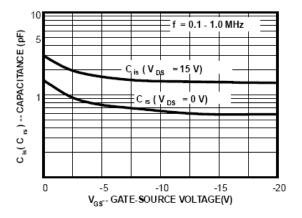


Figure 9. Capacitance vs. Voltage

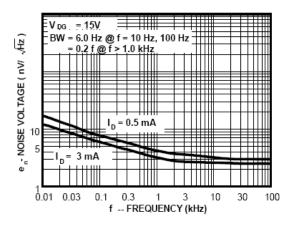


Figure 8. Noise Voltage vs. Frequency

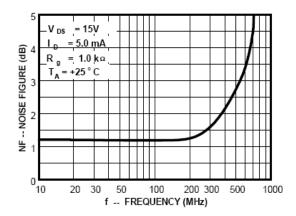


Figure 10. Noise Figure Frequency

COMMON SOURCE CHARACTERISTICS

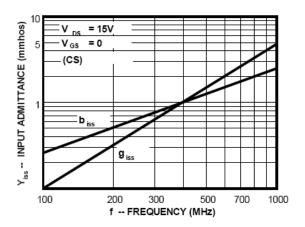


Figure 11. Input Admittance

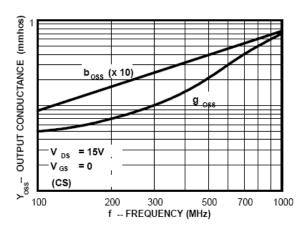


Figure 12. Output Admittance

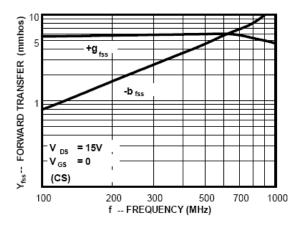


Figure 13. Forward Transadmittance

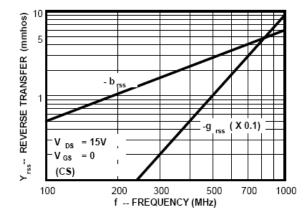


Figure 14. Reverse Transadmittance

COMMON GATE CHARACTERISTICS

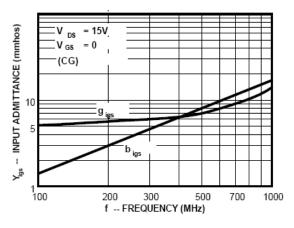


Figure 15. Input Admittance

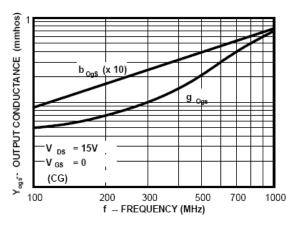


Figure 16. Output Admittance

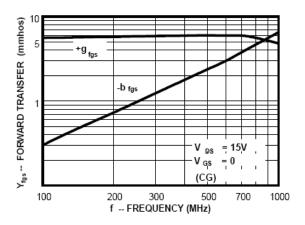


Figure 17. Forward Transadmittance

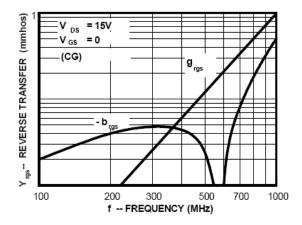


Figure 18. Reverse Transadmittance

MILLIMETERS

MIN

0.89

0.01

0.37

0.08

2.80

1.20

1.78

0.30

0.35

2.10

O°

NOM

1.00

0.06

0.44

0.14

2.90

1.30

1.90

0.43

0.54

2.40





SOT-23 (TO-236) 2.90x1.30x1.00 1.90P **CASE 318 ISSUE AU**

DATE 14 AUG 2024

MAX

1.11

0.10

0.50

0.20

3.04

1.40

2.04

0.55

0.69

2.64

10°

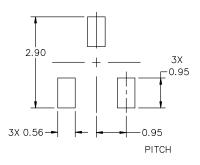




DETAIL "A" Scale 3:1







NOTES:

DIM

Α

Α1

b

С

D

Ε

е L

L1

HE

Τ

- DIMENSIONING AND TOLERANCING 1. PER ASME Y14.5M, 2018. CONTROLLING DIMENSIONS:
- MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42226B	the Document Repository. OCOPY" in red.	
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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

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DATE 14 AUG 2024

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR			
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	2. CATHODE 2.	2: STYLE 13: CATHODE PIN 1. SOURCE CATHODE 2. DRAIN ANODE 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	2. ANODE 2.	3: STYLE 19: NO CONNECTION PIN 1. CATHODE CATHODE 2. ANODE ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT			STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE			

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